Vincotech

80-M1126PA010M7-K217F70
datasheet

MiniSKiiP® PACK 1 — **1200 V / 10 A**

Features

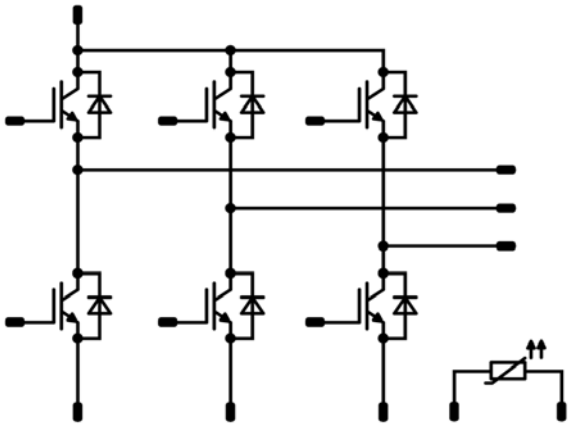
- IGBT M7 with low V_{CEsat} and improved EMC behavior
- Open emitter configuration
- Solder-free spring contact technology
- Built-in PTC

MiniSkiip® 1

Target applications

- Industrial Drives
- Embedded Drive

Schematic



Types

- 80-M1126PA010M7-K217F70

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	T_j = T_{jmax} T_s = 80 °C	10	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	20	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	67	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	T_j = T_{jmax} T_s = 80 °C	14	A
Repetitive peak forward current	I_{FRM}		20	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	53	W
Maximum junction temperature	T_{jmax}		175	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	5500	V
		AC Voltage t_p = 1 min	2500	V
Creepage distance		With std lid For more informations see handling instructions	6,3	mm
Clearance		With std lid For more informations see handling instructions	6,3	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,001	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		10	25 125 150		1,66 1,90 1,96	1,95	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			55	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		2000		pF
Output capacitance	C_{oes}							86		
Reverse transfer capacitance	C_{res}							23		
Gate charge	Q_g		15	600	10	25		80		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						1,41		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{goff} = 32 Ω R_{gon} = 32 Ω	±15	600	10	25 125 150		128 126 123		ns
Rise time	t_r					25 125 150		29 32 34		
Turn-off delay time	$t_{d(off)}$					25 125 150		145 179 182		
Fall time	t_f					25 125 150		98 108 117		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 1,1 µC Q_{rFWD} = 1,7 µC Q_{rFWD} = 1,8 µC				25 125 150		0,883 1,125 1,189		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		0,656 0,860 0,908		

Characteristic Values

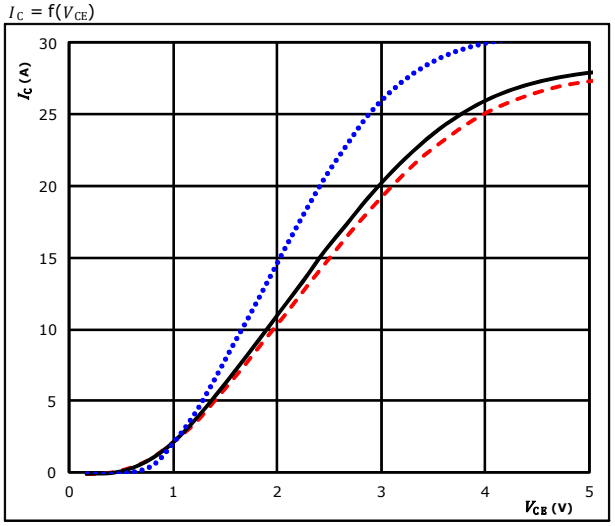
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				10	25 125 150		1,61 1,69 1,69	2,1	V
Reverse leakage current	I_R			1200		25			25	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						1,80		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 278 A/µs di/dt = 270 A/µs di/dt = 272 A/µs	±15	600	10	25 125 150		9 9 9		A
Reverse recovery time	t_{rr}					25 125 150		254 373 409		ns
Recovered charge	Q_r					25 125 150		1,088 1,664 1,808		µC
Reverse recovered energy	E_{rec}					25 125 150		0,374 0,620 0,680		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		85 54 49		A/µs
Thermistor										
Rated resistance	R					25		1		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1670 Ω				100	-2		+2	%
R_{100}	R					100		1670		Ω
Power dissipation constant						25		0,76		mW/K
A-value	$A_{(25/50)}$					25		$7,635*10^{-3}$		1/K
B-value	$B_{(25/100)}$					25		$1,731*10^{-5}$		1/K²
Vincotech PTC Reference									E	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

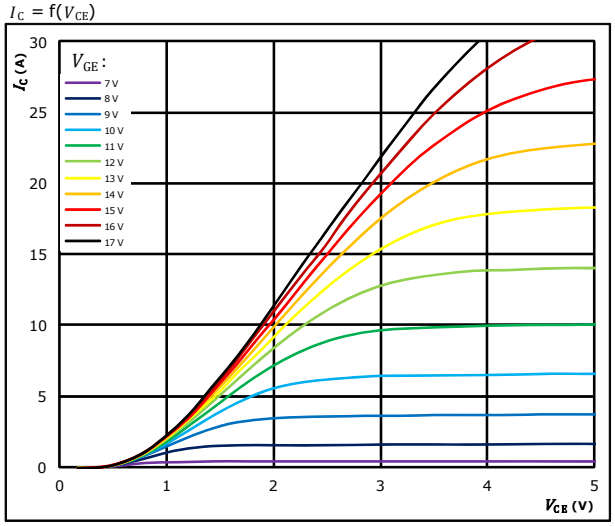


t_p =	250	µs		25 °C	
V_{GE} =	15	V	T_j:	125 °C	
				150 °C	

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

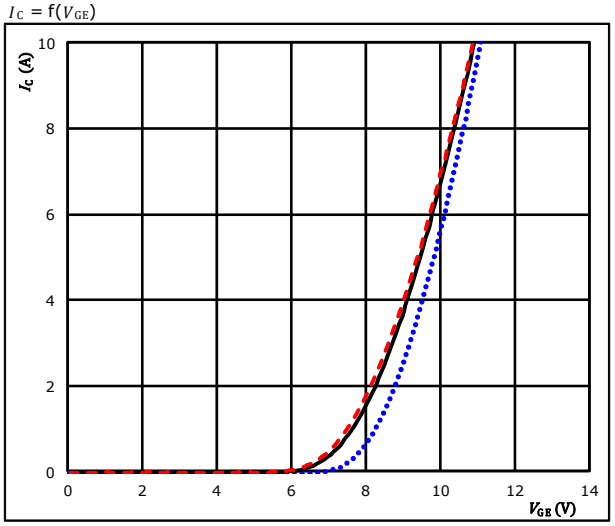


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

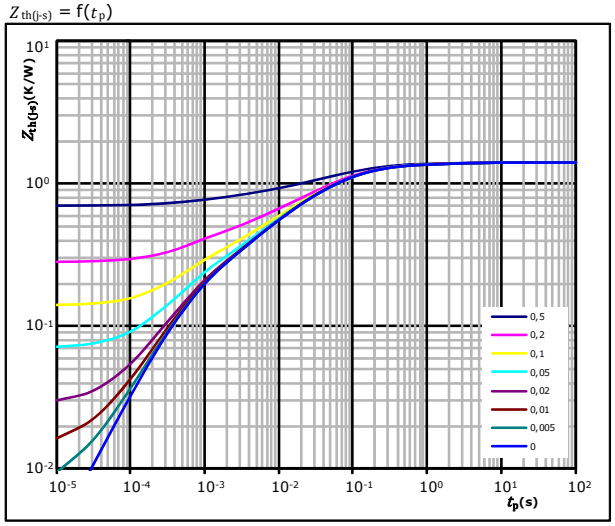


t_p =	100	µs		25 °C	
V_{CE} =	10	V	T_j:	125 °C	
				150 °C	

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	1,41	K/W

IGBT thermal model values

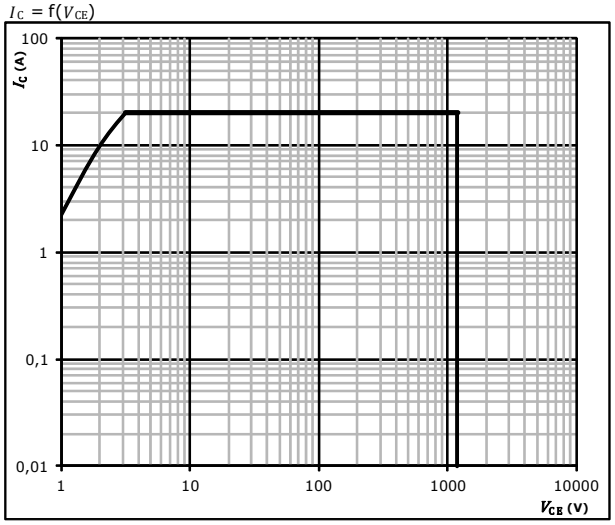
R (K/W)	τ (s)
6,61E-02	1,89E+00
1,81E-01	2,00E-01
5,32E-01	4,93E-02
3,21E-01	1,08E-02
1,59E-01	2,58E-03
1,49E-01	4,46E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



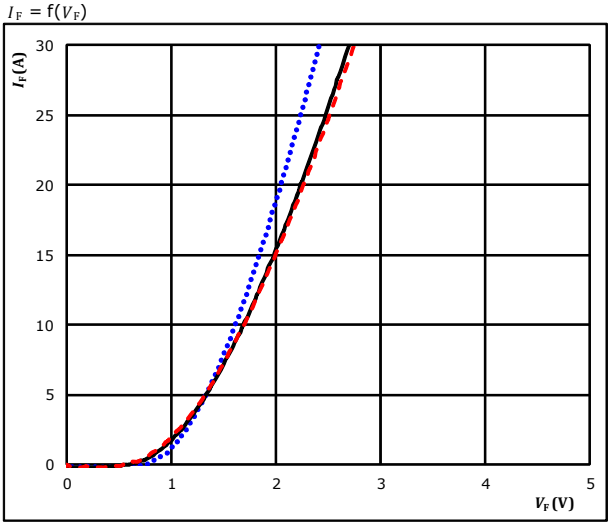
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



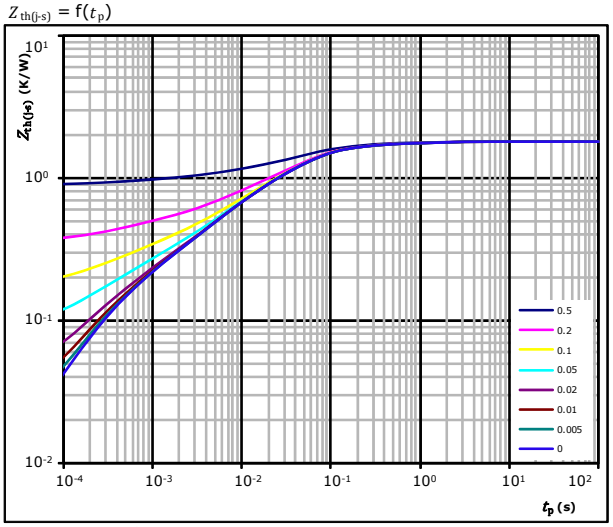
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,80 K/W

FWD thermal model values

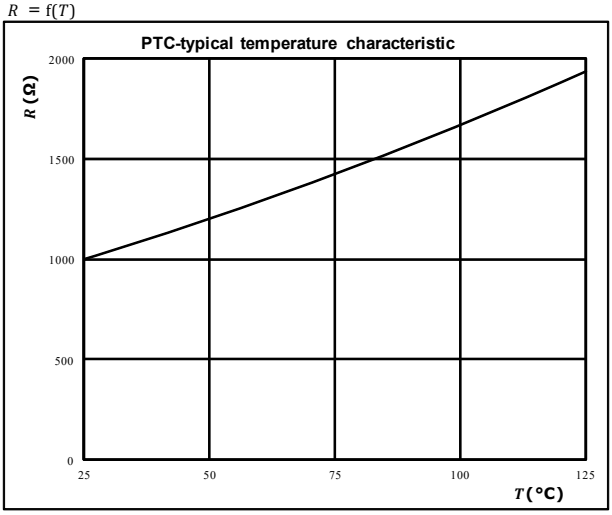
R (K/W)	τ (s)
9,72E-02	1,16E+00
2,38E-01	1,67E-01
9,04E-01	4,46E-02
3,13E-01	8,53E-03
1,25E-01	2,30E-03
1,19E-01	3,66E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical PTC characteristic
as a function of temperature

$R = f(T)$

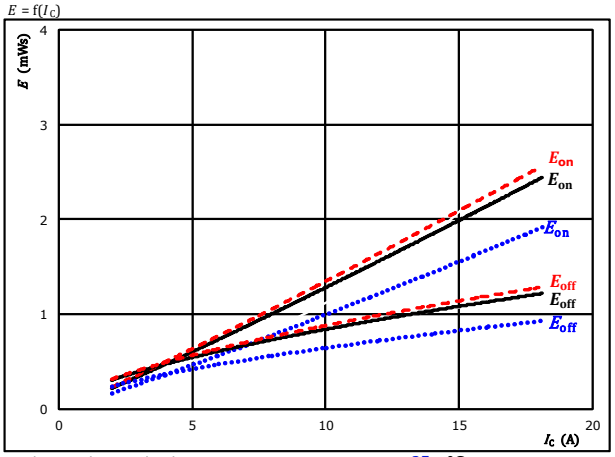


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



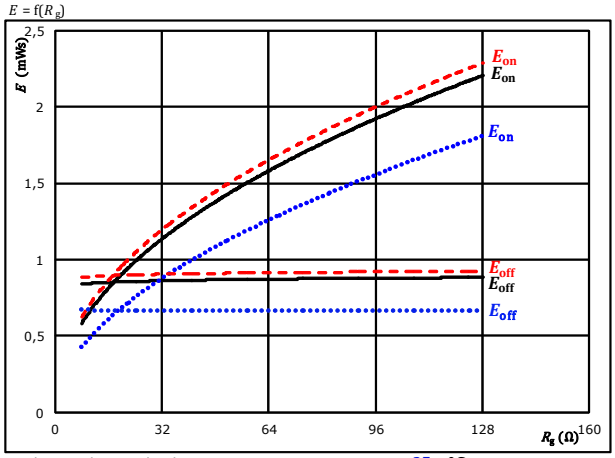
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
R_{gon} =	32	Ω		150 °C	
R_{goff} =	32	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



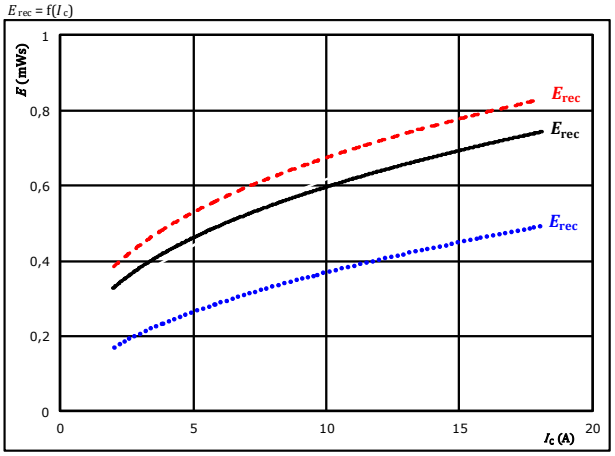
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
I_C =	10	A		150 °C	

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



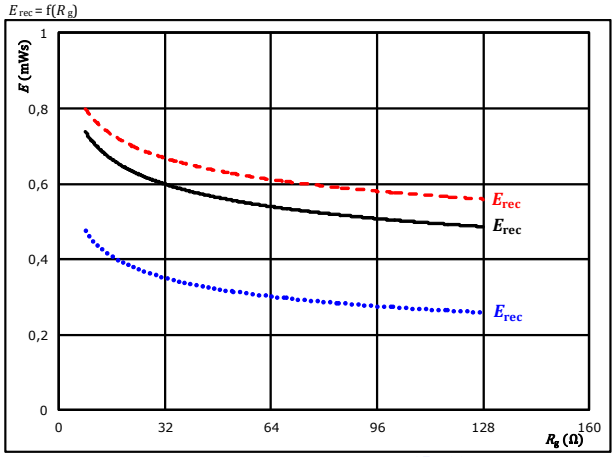
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
R_{gon} =	32	Ω		150 °C	

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

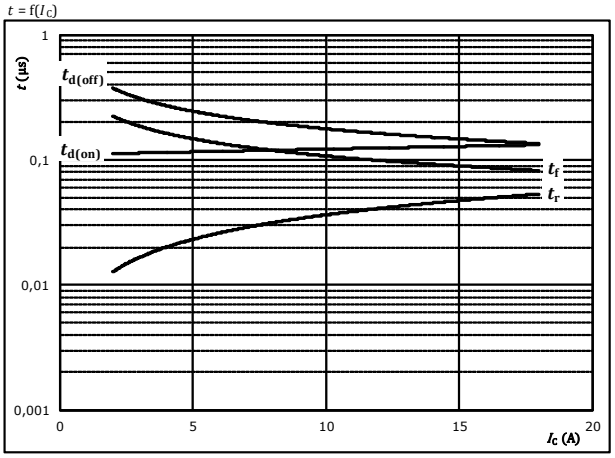
V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
I_C =	10	A		150 °C	

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



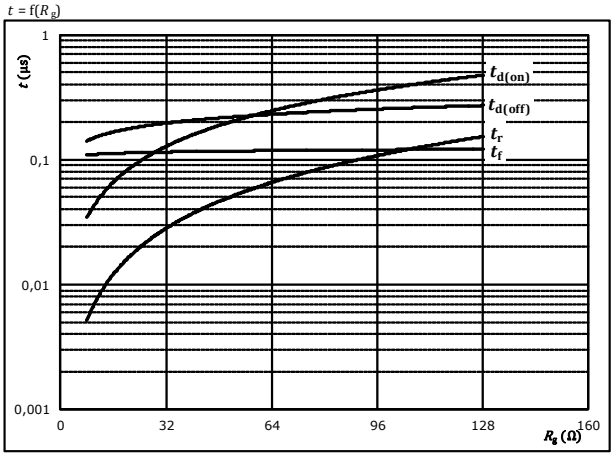
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



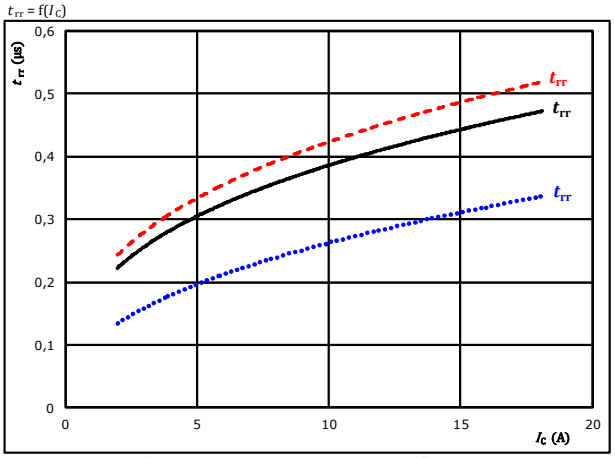
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	10	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



At

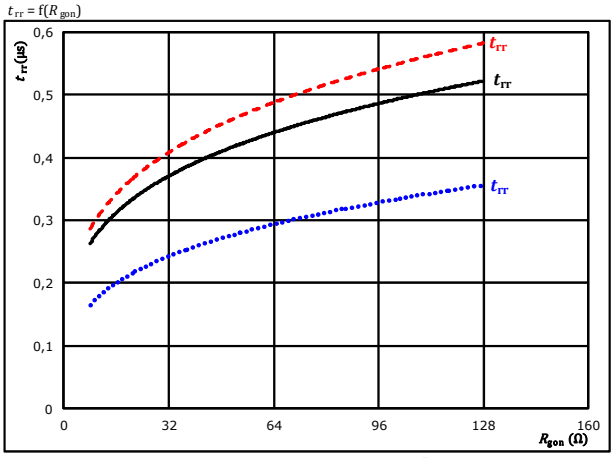
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



At

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	10	A

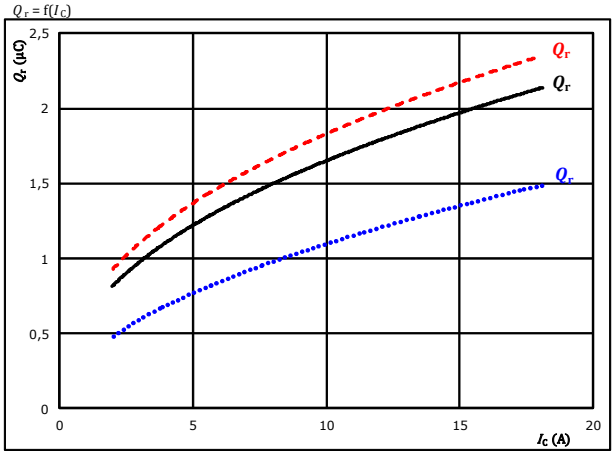
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

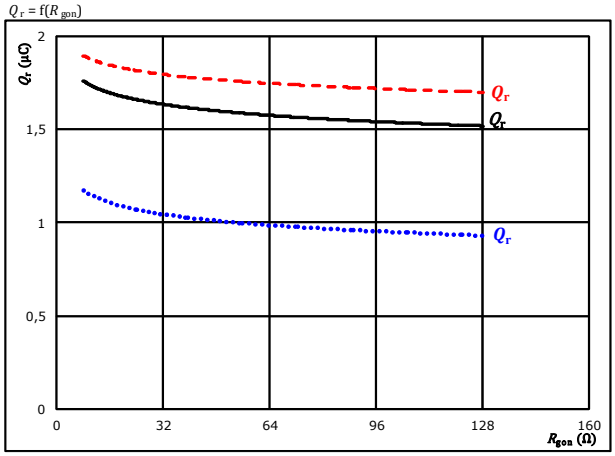


At						
	V_{CE} =	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	R_{gon} =	32	Ω		150 °C	

figure 10. **FWD**

Typical recoved charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

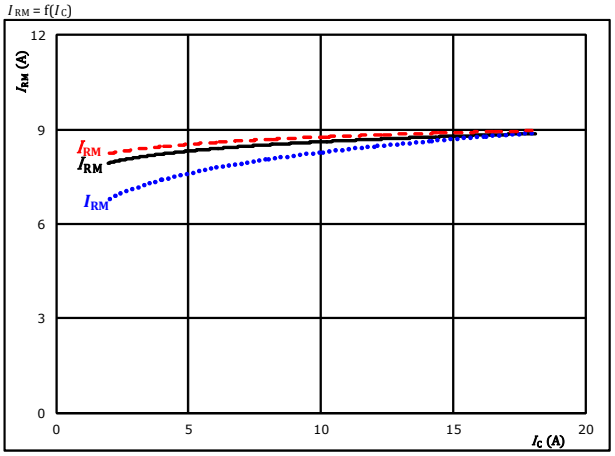


At						
	V_{CE}=	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	I_C=	10	A		150 °C	

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

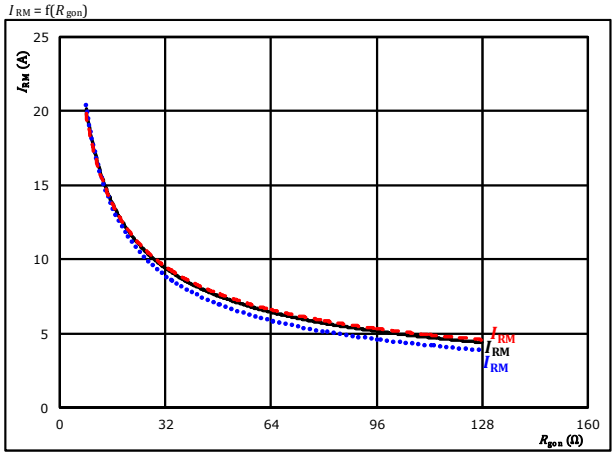


At						
	V_{CE}:	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	R_{gon} =	32	Ω		150 °C	

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



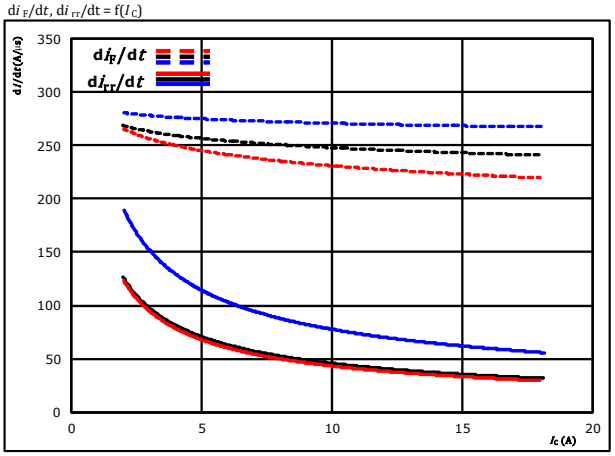
At						
	V_{CE} =	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	I_C =	10	A		150 °C	

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$

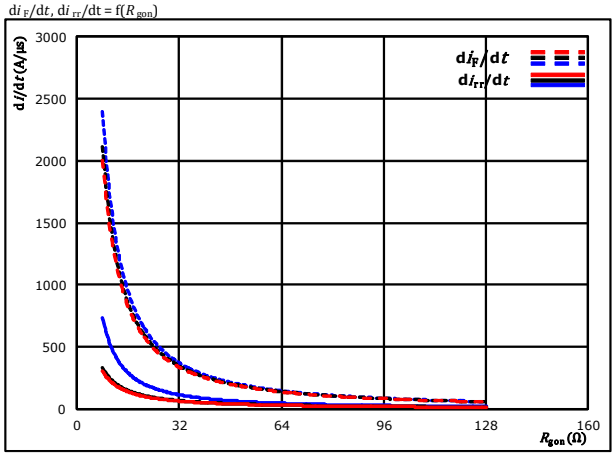


At						
V_{CE}:	600	V		25	°C	•••••••••••••
V_{GE} =	±15	V	T_j:	125	°C	———
R_{gon} =	32	Ω		150	°C	– – – –

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$

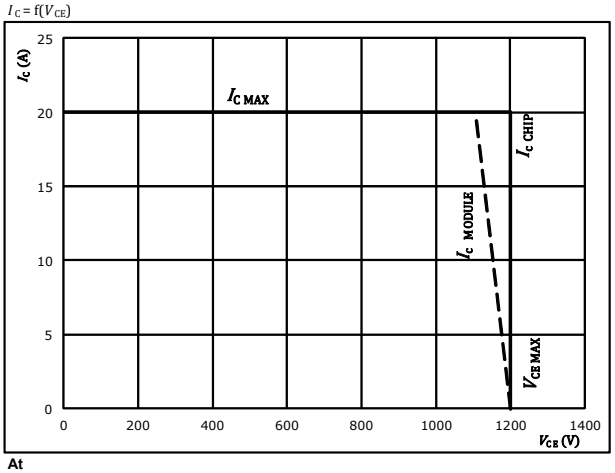


At						
V_{CE} =	600	V		25	°C	•••••••••••••
V_{GE} =	±15	V	T_j:	125	°C	———
I_C=	10	A		150	°C	– – – –

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	175	°C
R_{gon} =	32	Ω
R_{goff} =	32	Ω

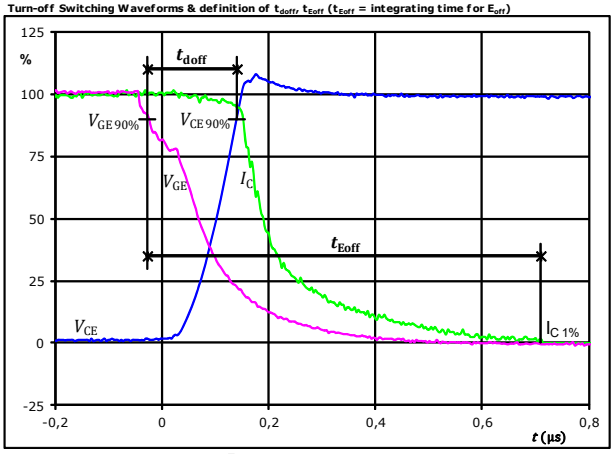
Inverter Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

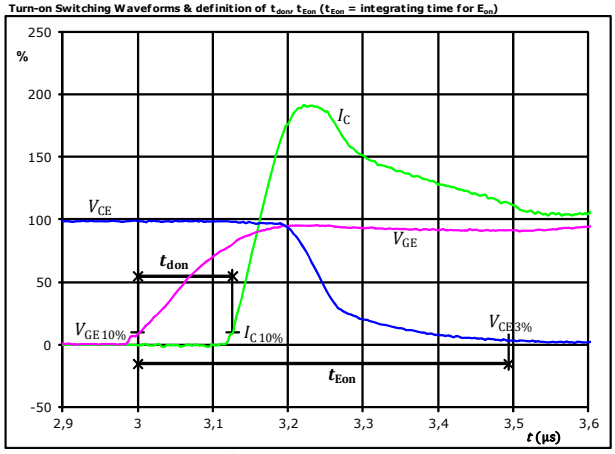
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	10	A
t_{doff} =	0,179	µs
t_{Eoff} =	0,737	µs

figure 2. IGBT

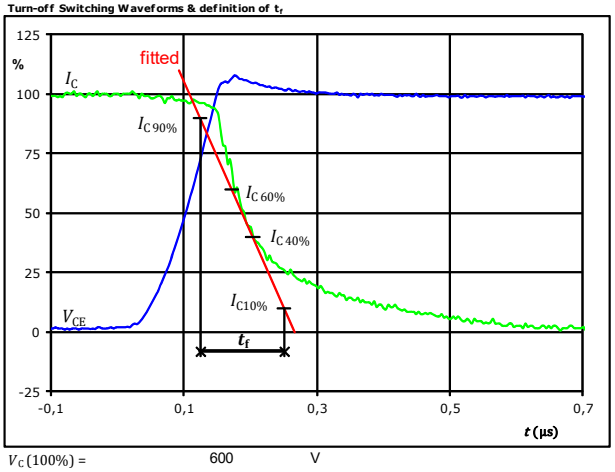
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	10	A
t_{don} =	0,126	µs
t_{Eon} =	0,493	µs

figure 3. IGBT

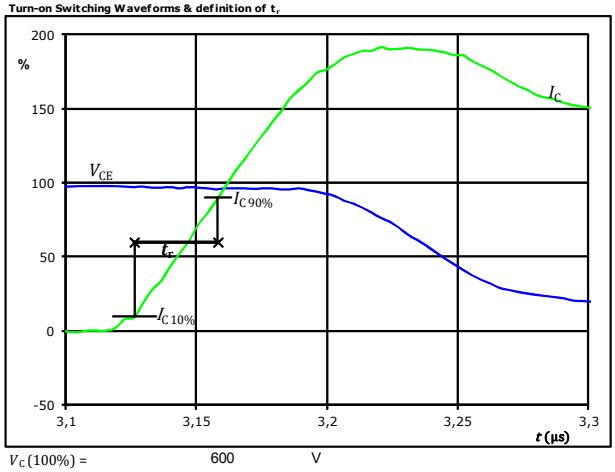
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	10	A
t_f =	0,108	µs

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

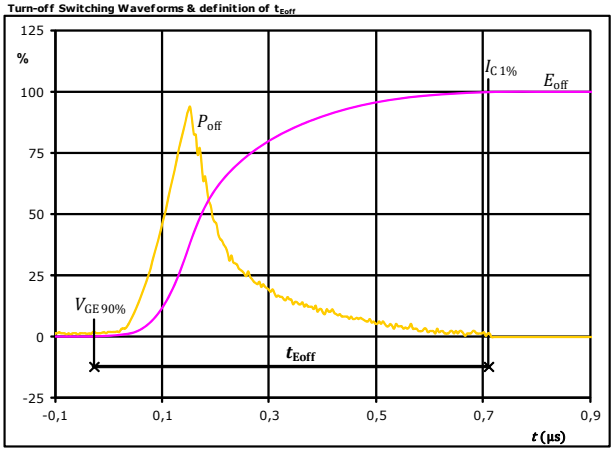


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	10	A
t_r =	0,032	µs

Inverter Switching Characteristics

figure 5. **IGBT**

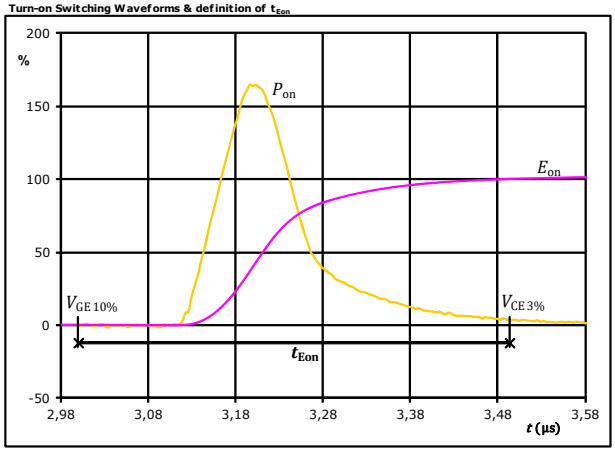
Turn-off Switching Waveforms & definition of t_{Eoff}



$P_{off}(100\%)$ =	6,02	kW
$E_{off}(100\%)$ =	0,86	mJ
t_{Eoff} =	0,74	µs

figure 6. **IGBT**

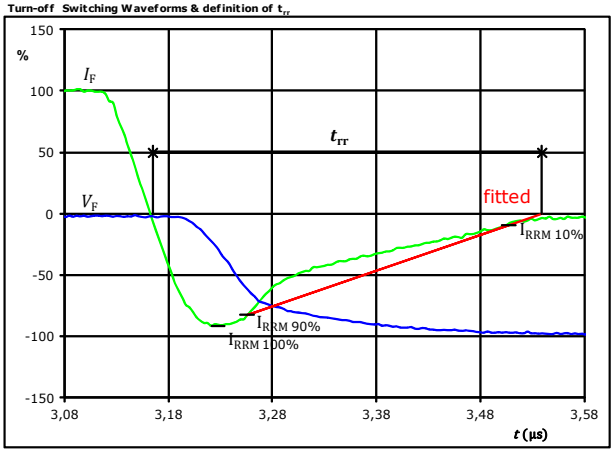
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on}(100\%)$ =	6,02	kW
$E_{on}(100\%)$ =	1,13	mJ
t_{Eon} =	0,49	µs

figure 7. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

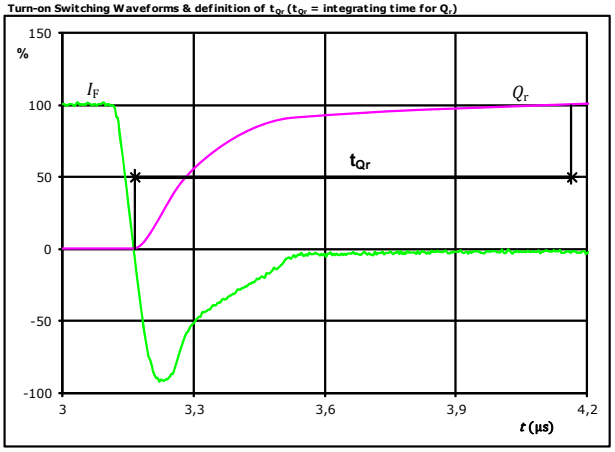


$V_F(100\%)$ =	600	V
$I_F(100\%)$ =	10	A
$I_{RRM}(100\%)$ =	-9	A
t_{rr} =	0,373	µs

Inverter Switching Characteristics

figure 8. **FWD**

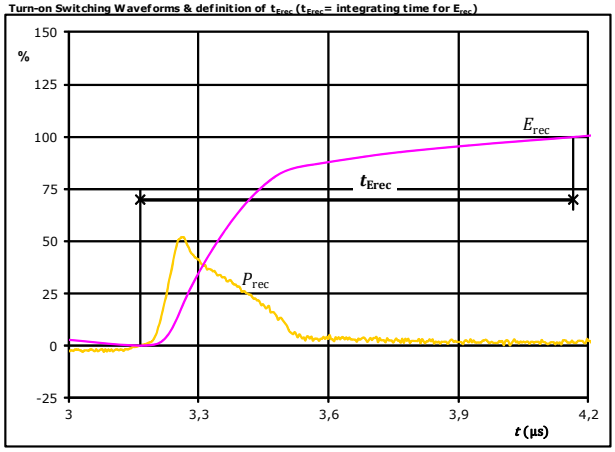
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	10	A
Q_r (100%) =	1,66	µC
t_{Qr} =	1,00	µs

figure 9. **FWD**

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec}= integrating time for E_{rec})



P_{rec} (100%) =	6,02	kW
E_{rec} (100%) =	0,62	mJ
t_{Erec} =	1,00	µs

Ordering Code & Marking

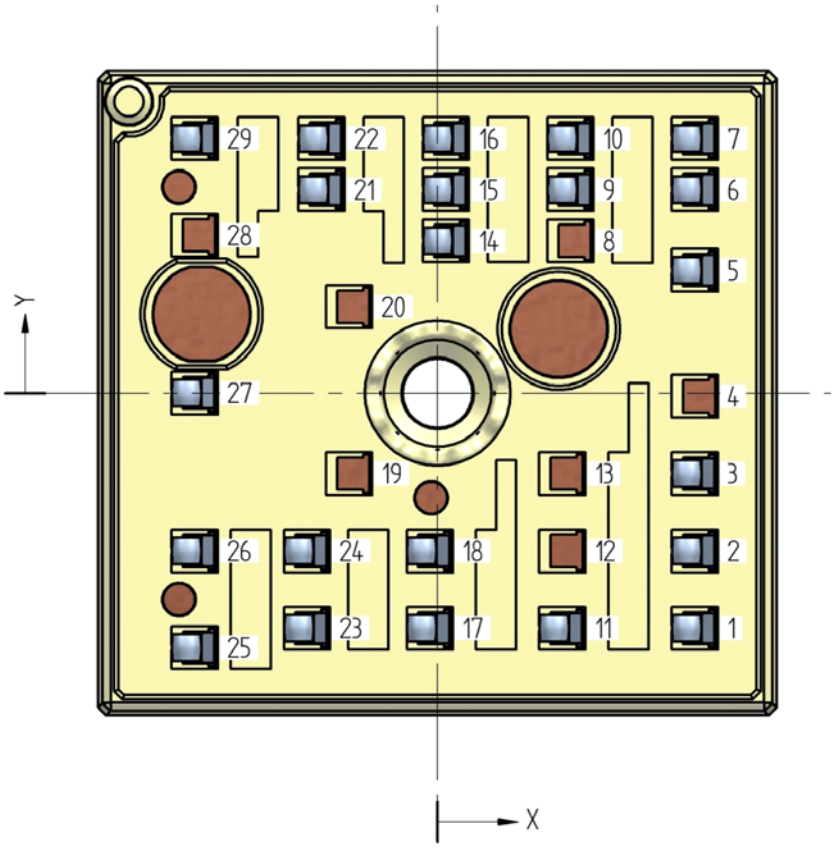
Version	Ordering Code
With std lid (6.5mm height) + no thermal grease	80-M1126PA010M7-K217F70-/0A/
With thin lid (2.8mm height) + no thermal grease	80-M1126PA010M7-K217F70-/0B/
With std lid (6.5mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	80-M1126PA010M7-K217F70-/1A/
With thin lid (2.8mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	80-M1126PA010M7-K217F70-/1B/
With std lid (6.5mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	80-M1126PA010M7-K217F70-/4A/
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	80-M1126PA010M7-K217F70-/4B/
With std lid (6.5mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	80-M1126PA010M7-K217F70-/5A/
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	80-M1126PA010M7-K217F70-/5B/

		Name	Date code	UL & VIN	Lot	Serial
Text		NN-NNNNNNNNNNNNN-TTTTTTVV	WWYY	UL VIN	LLLLL	SSSS
	Type&Ver	**Lot number**	**Serial**	**Date code**		
Datamatrix	TTTTTTVV	LLLLL	SSSS	WWYY		

Outline

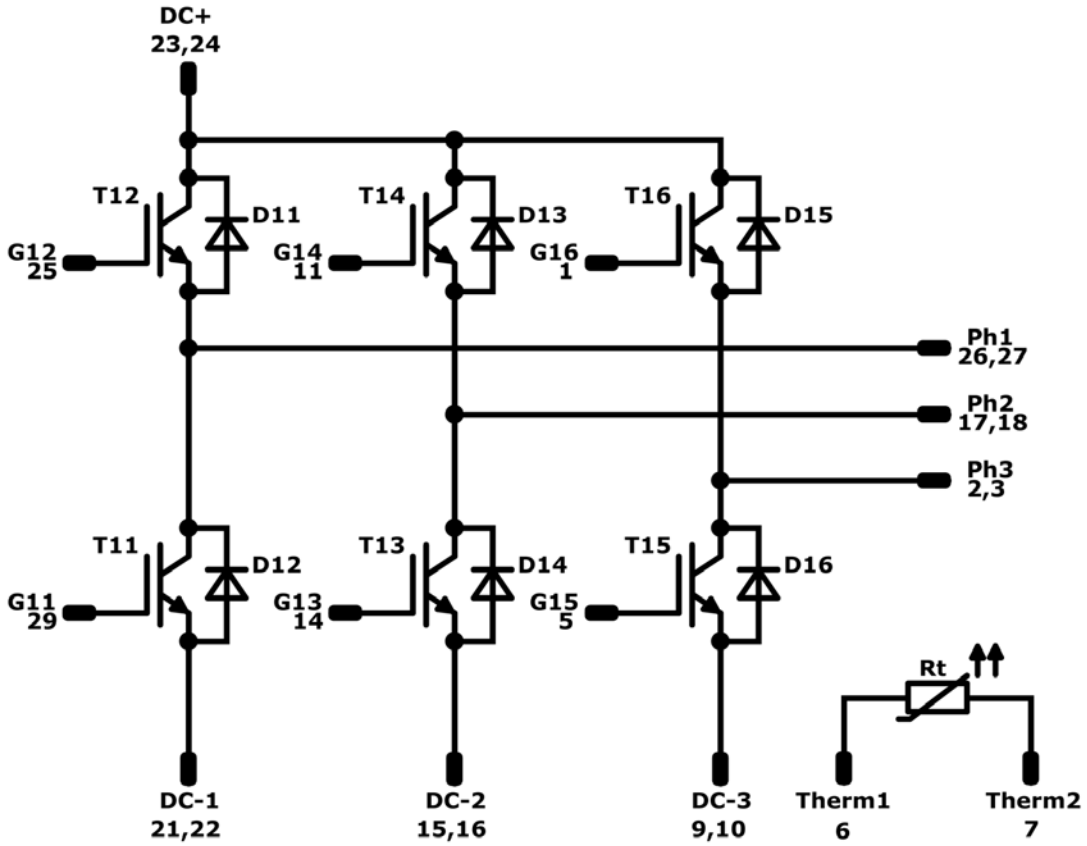
PCB pad table

Pin	X	Y	Function
1	15,93	-14,6	G16
2	15,93	-9,8	Ph3
3	15,93	-5	Ph3
4	Not assembled		
5	15,93	7,62	G15
6	15,93	12,62	Therm1
7	15,93	15,8	Therm2
8	Not assembled		
9	8,23	12,62	DC-3
10	8,23	15,8	DC-3
11	7,73	-14,6	G14
12	Not assembled		
13			
14	0,53	9,45	G13
15	0,53	12,62	DC-2
16	0,53	15,8	DC-2
17	-0,47	-14,6	Ph2
18	-0,47	-9,8	Ph2
19	Not assembled		
20			
21	-7,17	12,62	DC-1
22	-7,17	15,8	DC-1
23	-8,07	-14,6	DC+
24	-8,07	-9,8	DC+
25	-15,02	-15,8	G12
26	-15,02	-9,8	Ph1
27	-15,02	0	Ph1
28	Not assembled		
29	-15,02	15,8	G11



Pad positions refers to center point. For more informations on pad design please see package data

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	10 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	10 A	Inverter Diode	
Rt	PTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 120	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for MiniSkiiP® 1 packages see vincotech.com website.

Package data
Package data for MiniSkiiP® 1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
80-M1126PA010M7-K217F70-D1-14	09 Nov. 2017		